



Polo scientifico tecnologico

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BGA E855 HOT AIR AND IR SYSTEM



Features hot air TOP SYSTEM

1. Only 10s needed to desolder IC.
2. Can set password to protect menu from inadvertent changes.
3. Key-lock function available, protect parameters from inadvertent changes.
4. Excellent desoldering efficiency and speed. The whole process includes six programming phases, in which process parameters can be set according to needs.
5. 10 program channels available.
6. With vacuum suction pen, easy to use.
7. Large LCD display shows temperature, air volume, working time etc.
8. Temperature calibrates digitally, easy and convenient.
9. Magnetic switch or pedal switch available; easy to use.
10. Accurate temperature control; Closed-loop temperature control ensures temperature stability up to 2 .
11. Auto sleeping, energy-efficient. With the automatic cooling function, it can prolong the life of heating element and protect the unit.
12. Working time can be set with the range from 1-999s.

Specifications:

Rated Output:	1300W
Temperature Range:	100°C-500°C
Air Volume:	From 6-200l/min, Can set freely
Program Phase:	Six phases
Vacuum Suction Force:	0.03MP
Temperature Stability:	±2°C
Channel Quantity:	Ten
Anti-Static ESD Safe by design	

Features IR BOTTOM pre-heater:

1. Infrared ceramic heater, rapid heating, high efficiency, with a long service life.
2. K type thermocouple temperature control, closed loop with zero voltage heater switching, digital display, easy to operate.
3. With QUICK855PG used together, maintenance of SMD and BGA can be completed.
4. The arm can be moved easily and conveniently, easy to use.
5. Put the parts to be preheated on the stainless steel net or fixture of heating window(arranged in addition).
6. Two switches control power and heating separately. Also read the preheat plate temperature easily under the condition of un-heating.
7. Internal thermometer, convenient to test the temperature of PCB.
8. Can control external cooling fan.

Specifications:

Heating Power:	800W
Plate Area:	135*250mm
Plate Material:	Ceramic
Temperature Sensor:	K type Thermometer
Range of Adjustable Temperature:	50°C-350°C
Temperature Stability:	±1°C
Ambient Temperature:	0°C-40°C
Accuracy:	±8°C

Optional Side Camera

RPC Reflow Soldering Process Camera

Model:	RPC2005
Power:	About 15Watt
Camera:	22*10 times magnifying; 12V/300mA;
Horizontal resolution:	480 lines; PAL format

